

AMENDMENTS TO ABSTRACT

Please delete the original Abstract in its entirety and replace it with the following

Abstract:

Disclosed is a process for making a multilayer printed wiring board. Through holes are formed by irradiating light through a mask onto through hole portions of a photosensitive glass substrate, to create a latent image corresponding to the exposed portions. The glass of the exposed portions is removed. A heat-treatment is applied to crystallize the glass substrate having the through holes. A plurality of insulating layers and wiring layers are formed on each of the opposite surfaces of the crystallized glass substrate. The through holes are coated with a conductive film to provide conductive connection between the opposite surfaces of the glass substrate.